

AMENDMENTS TO THE CLAIMS:

Please cancel claim 24 without prejudice or disclaimer.

Claims 1-20. (Canceled)

Claim 21. (Currently amended) A method for manufacturing a group III nitride compound semiconductor device, comprising:

irradiating a surface of a wafer ~~comprising a group III nitride compound semiconductor~~ with ultraviolet rays to thereby clean a resist residue from said surface of said wafer, said surface comprising a group III nitride compound semiconductor,

wherein said ultraviolet rays cause a reaction of oxygen molecules to form stimulated oxygen atoms having a strong oxidative power at said surface of said wafer.

Claim 22. (Previously presented) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said ultraviolet rays have a central wavelength of 172 nm.

Claim 23. (Previously presented) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said ultraviolet rays are emitted from an excimer lamp.

Claim 24. (Canceled)

Claims 25 - 30. (Canceled)

Claim 31. (Currently amended) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said stimulated oxygen atoms oxidize an organic contamination on said surface of said wafer into CO, CO₂ and H₂O which flies up from said surface ~~of said light-emitting device.~~

Claim 32. (Currently amended) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, further comprising:
forming a resist layer on said a group III nitride compound semiconductor ~~layer~~; and
patterning said resist layer,
wherein said irradiating said surface of said wafer is performed after said patterning said resist layer.

Claim 33. (New) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said group III nitride compound semiconductor comprises a p-type semiconductor, and said irradiating said surface comprises irradiating a surface of said p-type semiconductor to clean a resist residue from said surface of said p-type semiconductor.

Claim 34. (New) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said oxygen molecules are supplied to said surface of said wafer by supplying an oxygen-containing gas to said surface.

Claim 35. (New) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said irradiating said surface of said wafer comprises locating said wafer in an area of an ultraviolet lamp unit which emits said ultraviolet rays.

Claim 36. (New) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said irradiating said surface of said wafer comprises irradiating an entirety of said surface of said wafer.

Claim 37. (New) A method for manufacturing a group III nitride compound semiconductor device according to claim 21, wherein said irradiating said surface of said wafer comprises using said ultraviolet rays to cut a molecular chain of said resist residue, and reacting said stimulated oxygen atoms with said cut molecular chain to decompose said resist residue.

Claim 38. (New) A method for manufacturing a group III nitride compound semiconductor device, comprising:

irradiating a surface of a group III nitride compound semiconductor with ultraviolet rays to remove a resist residue from said surface,

wherein said ultraviolet rays:

cut a molecular chain of said resist residue; and

cause a reaction of oxygen molecules to form stimulated oxygen atoms having a strong oxidative power at said surface, said stimulated oxygen atoms reacting with said cut molecular chain to decompose said resist residue.